

**N-Ch 100V Fast Switching MOSFETs**
**General Description**

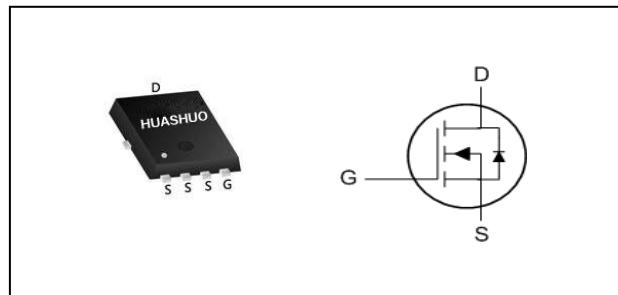
- 100% EAS Guaranteed
- Green Device Available
- Super Low RDS(ON)
- Advanced high cell density Trench technology

**Product Summary**

V <sub>DS</sub>	100	V
R <sub>DS(ON),typ</sub>	3.7	mΩ
I <sub>D</sub>	100	A

**Applications**

- MOTOR Driver.
- BMS.
- High frequency switching and synchronous rectification.

**PRPAK5\*6 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1,6</sub>	100	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1,6</sub>	95	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	480	A
EAS	Single Pulse Avalanche Energy <sub>3</sub>	702	mJ
I <sub>AS</sub>	Avalanche Current	53	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sub>4</sub>	208	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sub>1</sub>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sub>1</sub>	---	0.6	°C/W

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**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A	---	3.7	4.5	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0	3.0	4.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	10	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fS</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A	---	50	---	S
R <sub>G</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	1	---	Ω
Q <sub>G</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =20A	---	72	---	nC
Q <sub>GS</sub>	Gate-Source Charge		---	28	---	
Q <sub>GD</sub>	Gate-Drain Charge		---	15	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.0Ω, I <sub>D</sub> =20A	---	35	---	ns
T <sub>r</sub>	Rise Time		---	18	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	45	---	
T <sub>f</sub>	Fall Time		---	55	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz	---	4725	---	pF
C <sub>oss</sub>	Output Capacitance		---	609	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	14	---	

**Diode Characteristics**

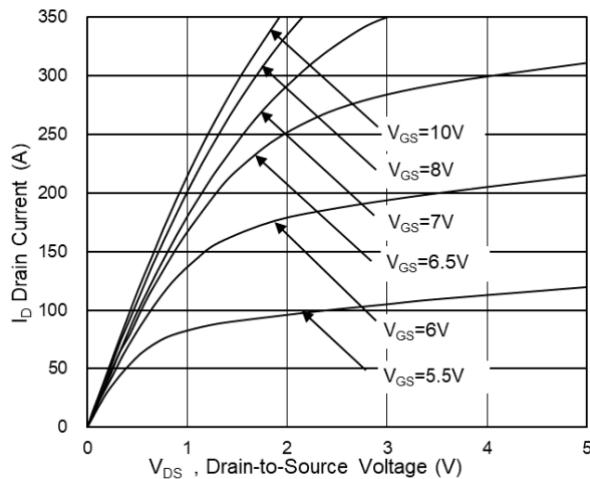
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =50A , T <sub>J</sub> =25°C	---	---	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =30A , dI/dt=100A/μs , T <sub>J</sub> =25°C	---	70	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	170	---	nC

Note :

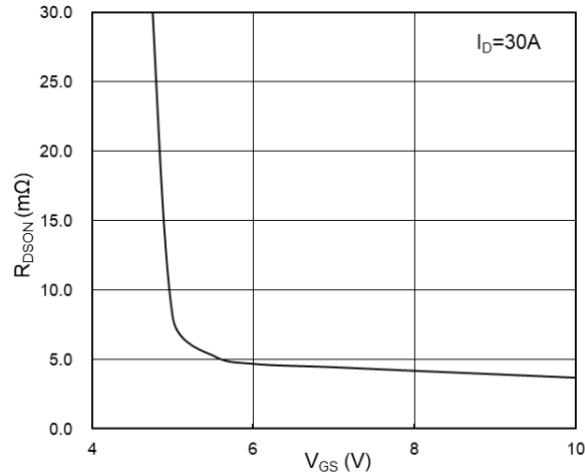
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.5mH,I<sub>AS</sub>=53A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.
- 6.Package limitation current.



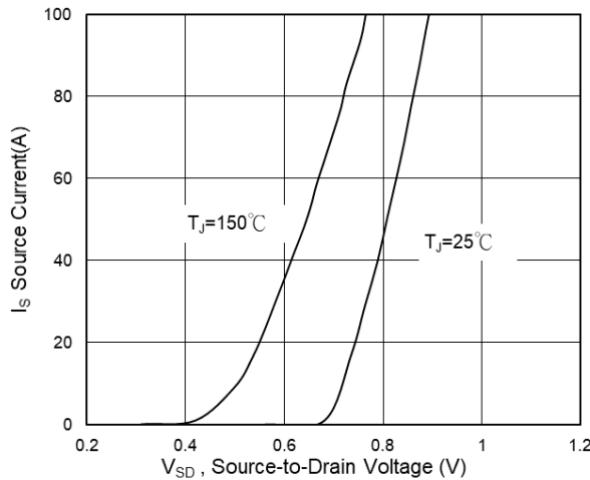
### Typical Characteristics



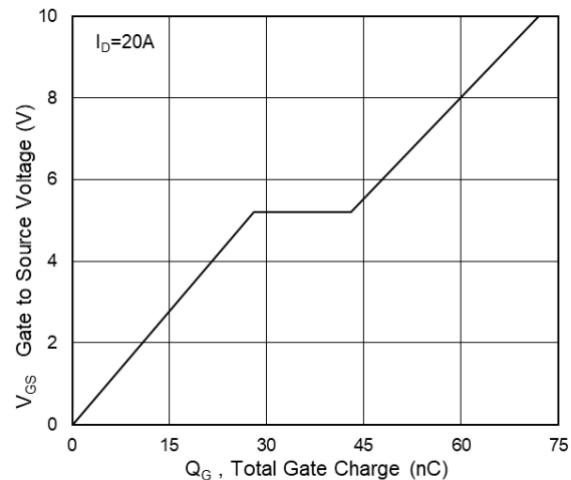
**Fig.1 Typical Output Characteristics**



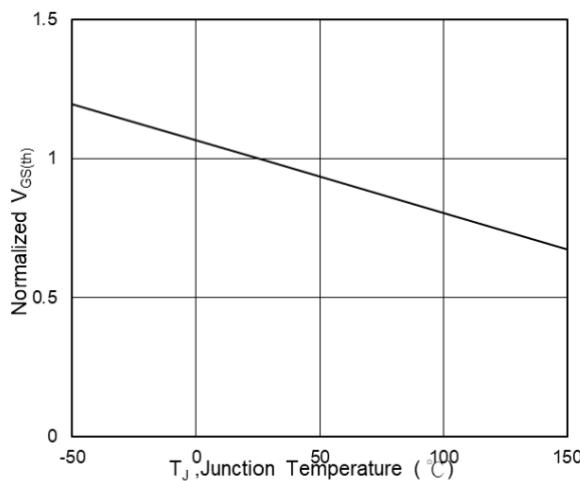
**Fig.2 On-Resistance vs G-S Voltage**



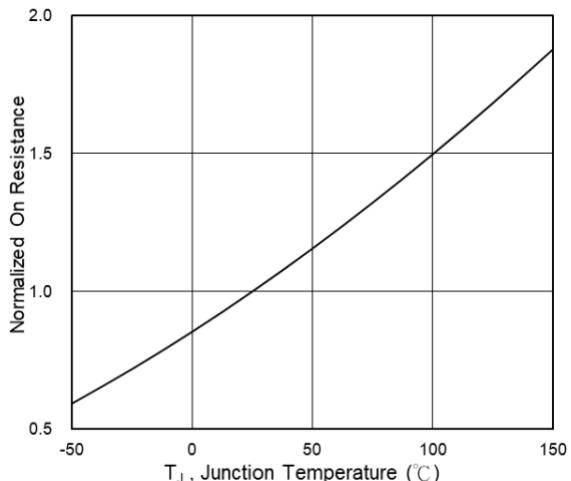
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{TH}$  vs  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



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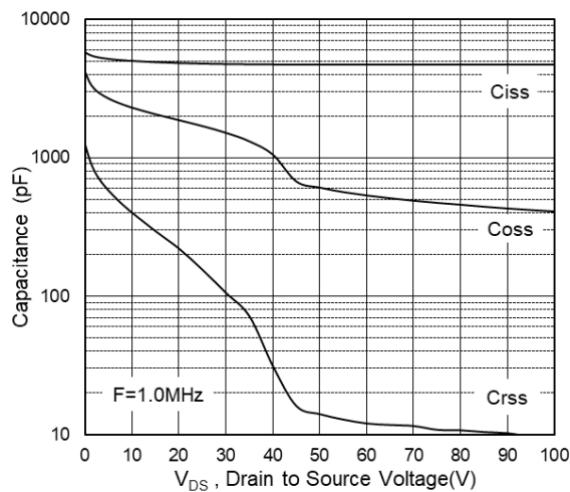


Fig.7 Capacitance

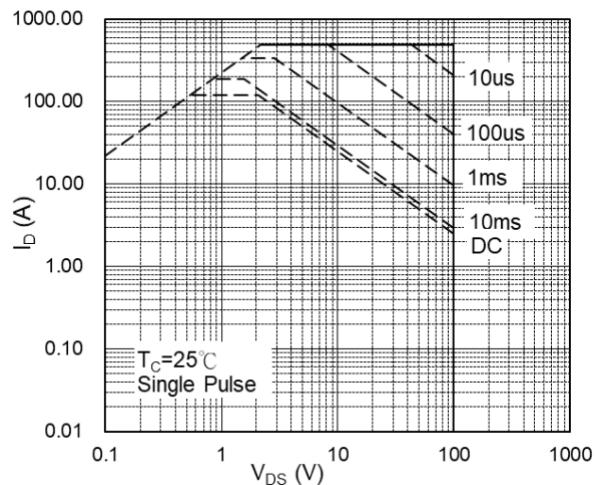


Fig.8 Safe Operating Area

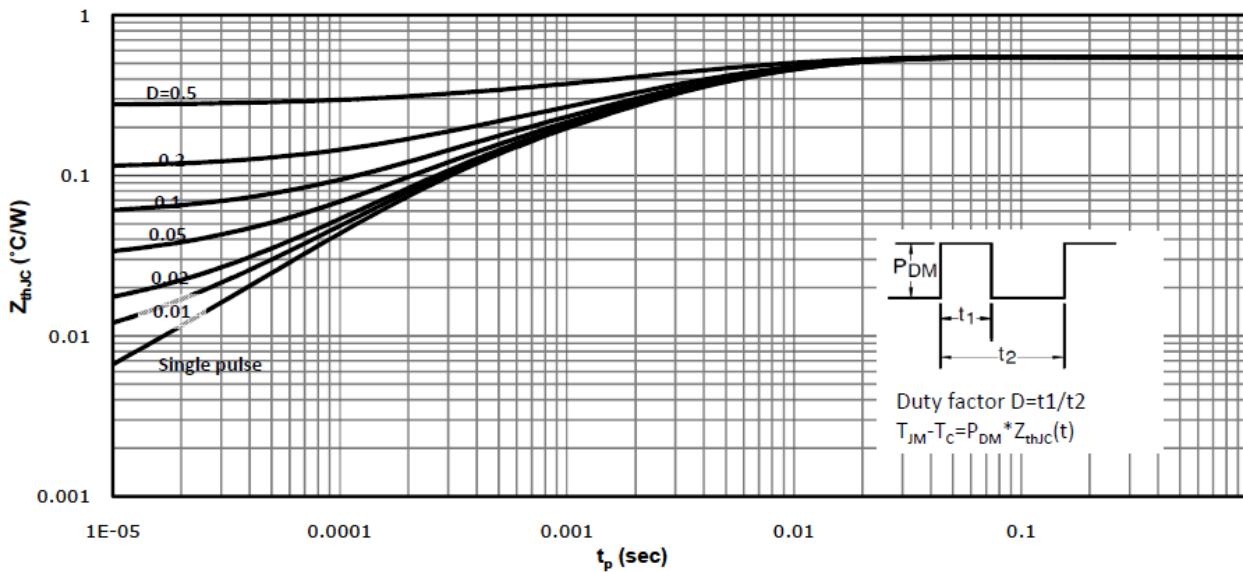


Fig.9 Normalized Maximum Transient Thermal Impedance

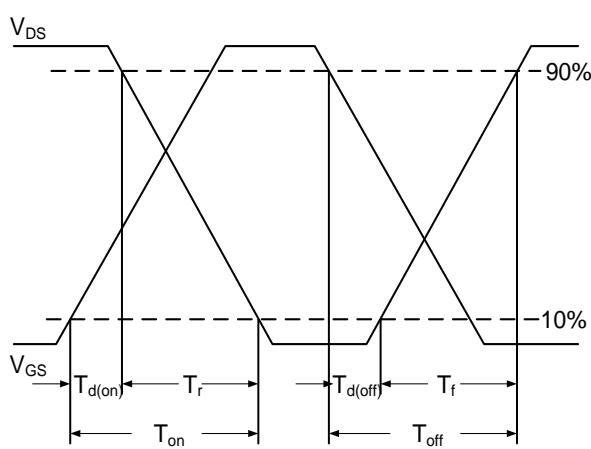


Fig.10 Switching Time Waveform

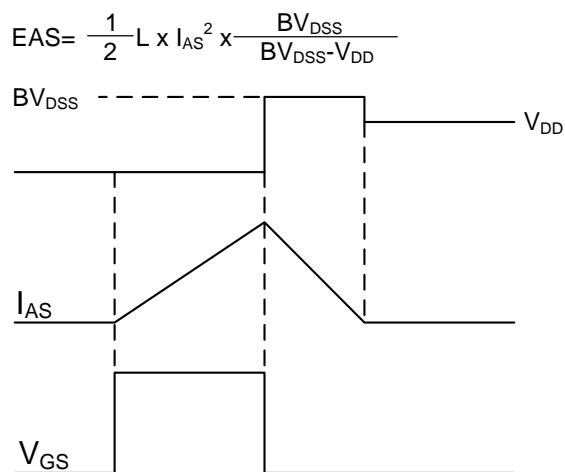
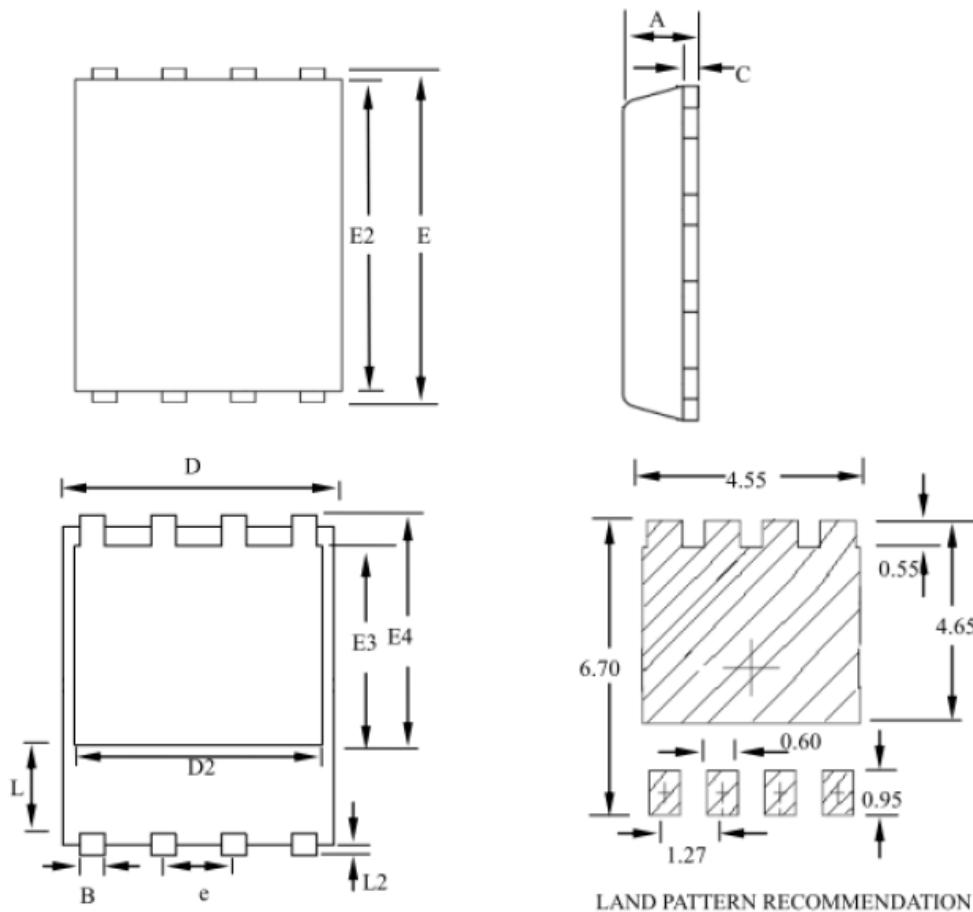


Fig.11 Unclamped Inductive Switching Waveform



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## PRPAK5X6 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--